

FBHA S Series Chip Ferrite Bead High Current Type Size 0805



FEATURES

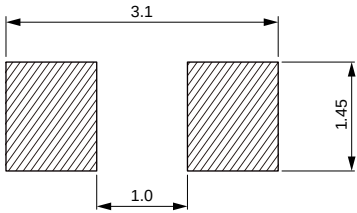
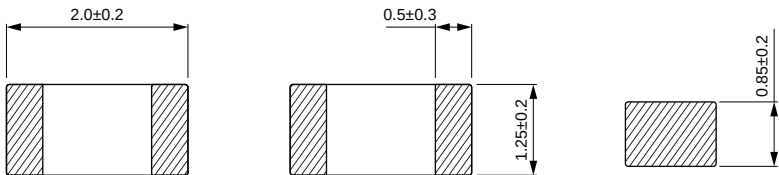
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APPLICATION

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Dimensions: [mm]

Land Pattern: [mm]

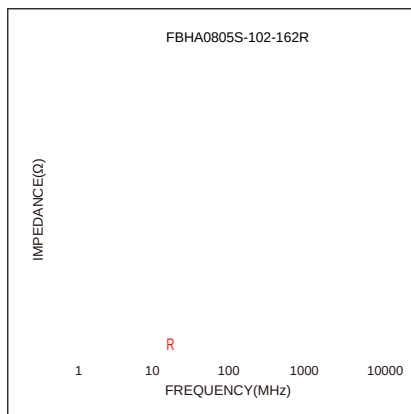
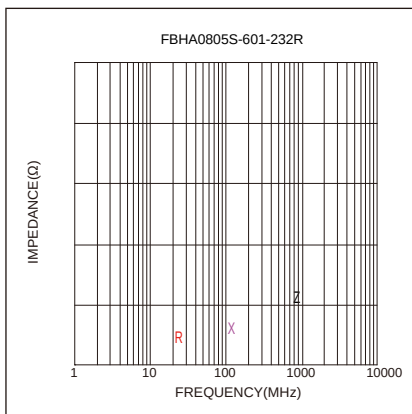
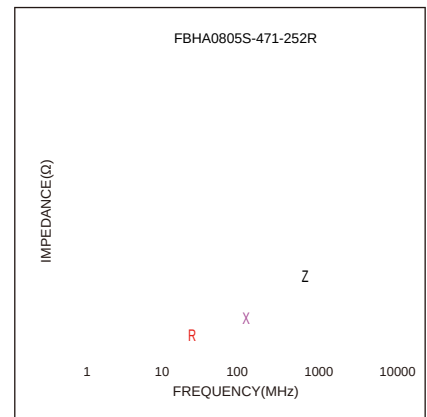
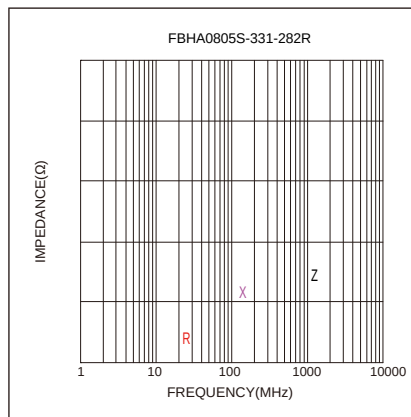
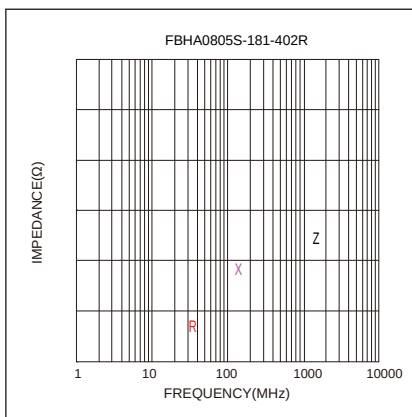
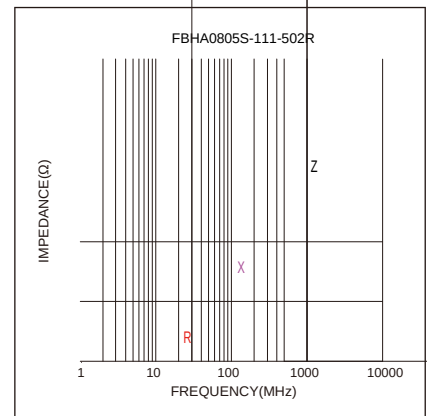
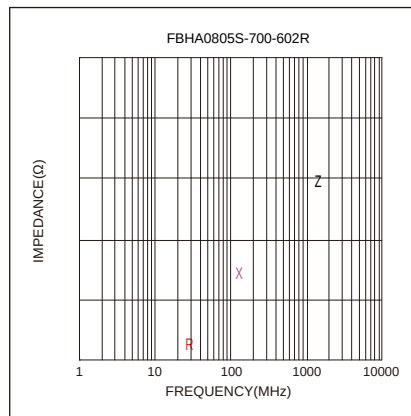
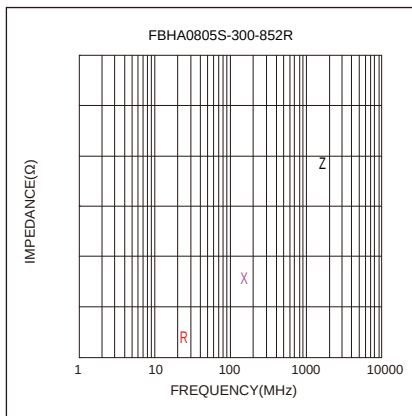


Electrical Properties:

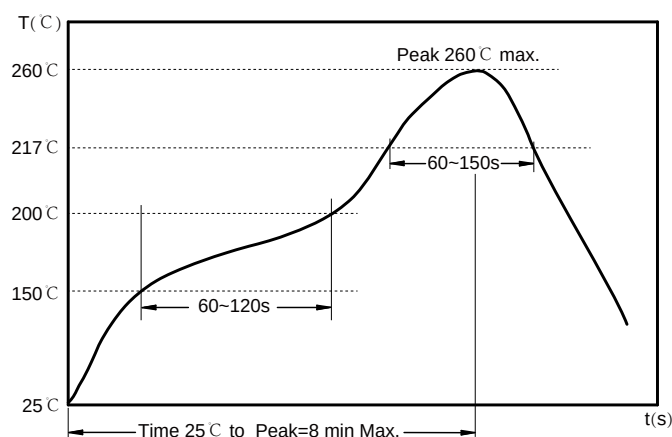
Part No	Impedance @ 100MHz	Tolerance	DC Resistance Max.	Temperature Rise Current Max.

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$

Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

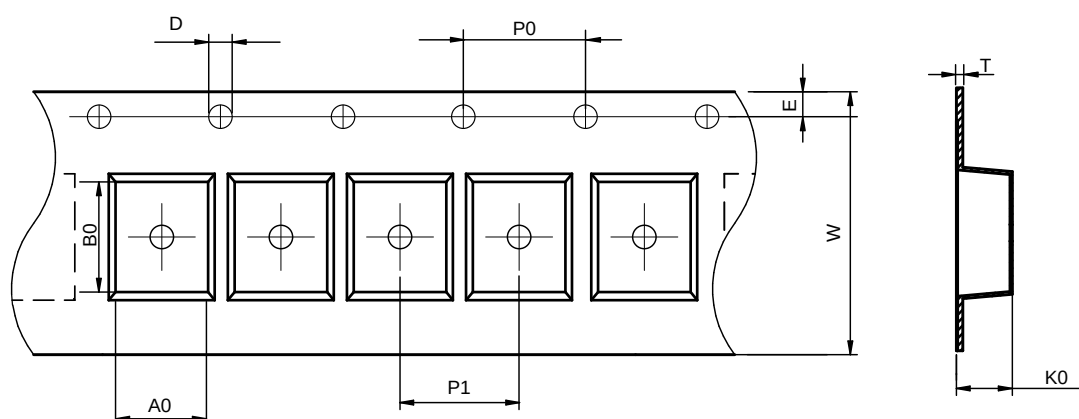
Allowed time above 217 °C: 60~150 sec.

Max temperature: 260 °C .

Allowed Reflow time: 3x max.

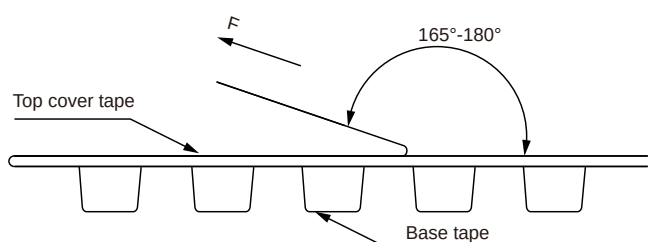
Packaging Information:

Tape Dimension:



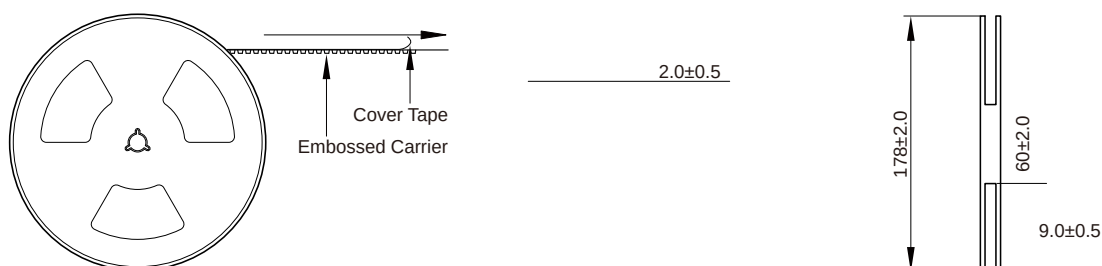
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
FBHA0805S	1.30±0.05	2.10±0.05	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.3	0.95±0.05	1.75±0.1	0.95±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.58 N

Reel Dimension: [mm]



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the

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Operation Instructions:

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